

**AMENDMENTS**

**IN THE CLAIMS:**

*Please cancel claims 22-27 as provided below.*

1-13. (Cancelled).

14. (Previously presented) A photodiode arrangement, comprising:  
a photodiode; and  
a submount that is electrically contact-connected to the photodiode,  
wherein the photodiode comprises a metallization on a side facing the submount,  
the submount comprises a metallization on a side facing the photodiode, and  
the photodiode and the submount are connected to one another by means of eutectic  
bonding.

15. (Previously presented) The arrangement as claimed in claim 14, further  
comprising one or more alignment marks situated on the photodiode or the submount  
or on both the photodiode and the submount.

16. (Previously presented) The arrangement as claimed in claim 14, wherein the  
photodiode or the submount or both comprise a silicon chip.

17. (Previously presented) The arrangement as claimed in claim 14, wherein the  
photodiode and the submount each have an outer contour that differs from one another  
and, accordingly, comprise regions that protrude relative to one another.

18. (Previously presented) The arrangement as claimed in claim 17, further  
comprising contact pads situated on a region of the submount that protrudes with

respect to the photodiode, wherein said contact pads are connected to the metallization of the submount.

19. (Previously presented) The arrangement as claimed in claim 17, wherein the photodiode comprises an optically active area situated on a region of the photodiode that protrudes with respect to the submount.

20. (Previously presented) The arrangement as claimed in claim 14, wherein the metallization of the photodiode comprises a gold metallization and the metallization of the submount comprises a gold-tin metallization, or vice versa.

21. (Previously presented) The arrangement as claimed in claim 14, wherein one of the photodiode and the submount comprise a trench or cutout on the side facing the other of the photodiode and the submount, thereby ensuring a connection between the photodiode and the submount only in defined regions not associated with the trench.

22-27. (Canceled).